

Datos OMNIMATE - Transformador de conectores RJ45 RJ45M R1D 3.3N4Y/G TY

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Conectores hembra de transmisores RJ45 (magnéticos) para aplicaciones de gigabit (1000 base-T) con compensación integrada contrarrestan activamente acoplamientos inductivos y capacitivos y ahorran espacio en el PCB.

- Procedimientos de soldadura THT o THR
- Amplia gama de diferentes tipos de diseño, también con LED integrados y lengüetas de contacto de apantallado
- Embalaje en bandeja (TY) o en rollo (embalaje en cinta, RL)
- Rango de temperaturas ampliado de -40 °C a +85 °C
- Capa de oro reforzada para protección mejorada contra la corrosión
- Velocidades de transmisión de hasta 1 Gbit/s

Datos generales para pedido

Tipo	RJ45M R1D 3.3N4Y/G TY
Código	2461060000
Versión	Conector para placa c.i., Transformador de conectores RJ45, 10/100 MBit/s, Conexión por soldadura THT/THR, 90°, Opción de bloqueo: inferior, Anilla de apantallado: ninguno, 30-80 µ" Ni / 30- µ" Au, LED: Sí, amarillo, verde, Número de polos: 8, Bandeja (conjunto manual)
GTIN (EAN)	4050118476439
U.E.	120 Pieza
Embalaje	Bandeja (conjunto manual)

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Datos técnicos

Dimensiones y pesos

Anchura	15,9 mm	Anchura (pulgadas)	0,626 inch
Altura	16,8 mm	Altura (pulgadas)	0,661 inch
Altura construcción baja	13,5 mm	Profundidad	21,35 mm
Profundidad (pulgadas)	0,841 inch	Peso neto	3,45 g

Temperaturas

Temperatura de almacenamiento, max.	85 °C	Temperatura de almacenamiento, min.	-40 °C
Temperatura de servicio, max.	85 °C	Temperatura de servicio, min.	-40 °C

Conformidad medioambiental del producto

REACH SVHC	Lead 7439-92-1
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Especificaciones del sistema

Angulo de salida	90°	Anilla de apantallado	ninguno
Apantallamiento	Sí	Ciclos de enchufado	750
Color de LED derecho	verde	Color de LED izquierdo	amarillo
Familia del producto	Datos OMNIMATE - Transformador de conectores RJ45	LED	
Material del apantallamiento	Latón	Montaje sobre placas c.i.	Sí
Número de polos	8	Conexión por soldadura THT/THR	
Opción de bloqueo	inferior	Número de terminales de soldadura por polo	1
Paso en pulgadas (P)	0,05 inch	Paso en mm (P)	1,27 mm
Tipo de conexión	Conector hembra	Superficie de apantallado	níquelado
Velocidad de transmisión	10/100 MBit/s	Tipo de protección	IP20

Propiedades eléctricas

Intensidad nominal	1,5 A	Resistencia a tensiones eléctricas, contacto/apantallado	1500 V DC
Resistencia a tensiones eléctricas, contacto/contacto	1000 V DC	Resistencia de aislamiento	> 500 MΩ
Tensión nominal	125 V AC		

Datos del material

Materiales aislantes	PA 9T	Color	negro
Carta de colores (similar)	RAL 9011	Grupo de materiales aislantes	II
CTI	≥ 500	Resistencia de aislamiento	> 500 MΩ
Moisture Level (MSL)	1	Grado inflamabilidad según UL 94	V-0
Material del contacto	Fósforo, bronce	Superficie de contacto	Oro sobre níquel
Estructura de capas del contacto del conector	30-80 μ" Ni / 30- μ" Au	Temperatura de almacenamiento, min.	-40 °C
Temperatura de almacenamiento, max.	85 °C	Temperatura de servicio, min.	-40 °C
Temperatura de servicio, max.	85 °C		

Embalaje

Embalaje	Bandeja (conjunto manual)	Longitud de VPE	0 m
Anchura VPE	0 m	Altura de VPE	0 m

Fecha de creación 1 de agosto de 2019 14:06:19 CEST

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Datos técnicos

Clasificaciones

ETIM 6.0	EC002637	eClass 6.2	27-25-05-04
eClass 9.0	27-44-04-02	eClass 9.1	27-44-04-02

Homologaciones en línea

Homologaciones



ROHS Conformidad

Descargas

Datos de ingeniería	STEP
Documentación del usuario	MAN IE GUIDE DE MAN IE GUIDE EN
Notificación de cambio de producto	PCN PCN

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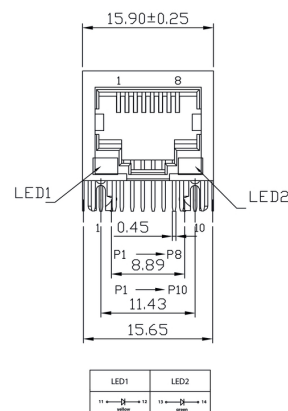
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Dibujos

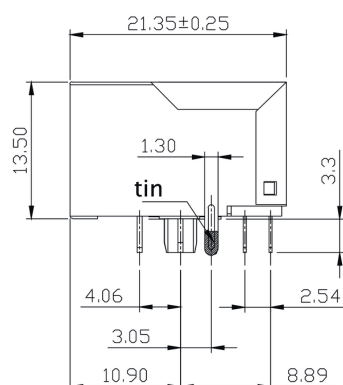
Dibujo acotado



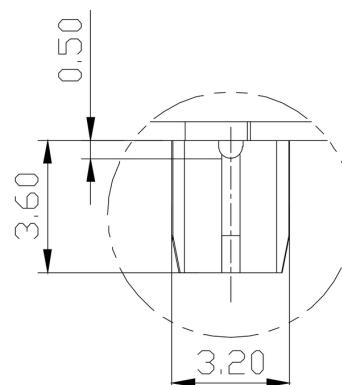
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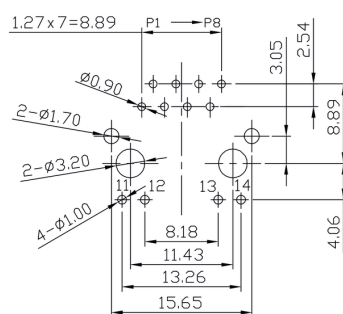
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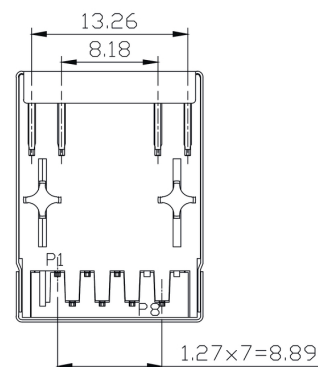


Diseño de la placa de circuito impreso



PCB Layout

Dibujo acotado

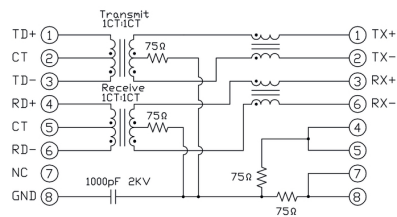


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Dibujos

Esquema de conexiones



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Dibujos

Gráfico

Characteristics

Inductance	350 µH min. @ 100 kHz, 100 mV, 8 mA DC Bias
Leakage Inductance	0.3 µH max. @ 100 kHz, 100 mV
Insertion Loss	1.1 dB max. @ (1 - 100) MHz
Return Loss	18 dB min. @ (1 - 30) MHz 16 dB min. @ (30 - 60) MHz 12 dB min. @ (60 - 80) MHz
Cross Talk	30 dB min. @ (1 - 100) MHz
Common Mode Rejection	30 dB min. @ (1 - 100) MHz

Códigos de tipo

RJ45	G1	R	1	U	3.2	E	4	GY/GY	TY	RJ45G1 R1U 3.2E4GY/GY TY																																																																																																																		
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Recommended wave soldering profiles

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Single Wave:



Double Wave:



Wave soldering profiles

Wired connection elements should be processed in accordance with the DIN EN 61760-1 standard. We have included two recommendations for practical wave soldering profiles, with which Weidmüller PCB terminals and connectors are qualified.

When choosing a suitable profile for your application, the following factors also need to be considered:

- PCB thickness
- Proportion of Cu in the layers
- Single/double-sided assembly
- Product range
- Heating and cooling rates

The single and double wave profiles each indicate the recommended operating range, including the maximum soldering temperature of 260°C. In practice, the maximum soldering temperature is quite often well below the above maximum profile.

We reserve the right to make technical changes.

Recommended reflow soldering profile

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Reflow soldering profile

The perfect soldering profile for SMT Surface Mount Technology is one the most exiting question in SMT production. But there are more than one correct answer: The diagram of temperature-on-time is related to processing features of solder paste and to maximum load of components.

We have to consider the following parameters:

- Time for pre heating
- Maximum temperature
- Time above melting point
- Time for cooling
- Maximum heating rate
- Maximum cooling rate

We recommend a typical solder profile with associated process limits. With preheating components and board are prepared smoothly for the solder phase. Heating rate is typically $\leq +3\text{K/s}$. In parallel the solder paste is 'activated'. The time above melting point of 217°C the paste gets liquid and components and boards begin to connect. The maximum temperature of 245°C to 254°C should stay between 10 and 40 seconds. In the cooling phase at $\geq -6\text{K/s}$ solder is cured. Board and components cool down while avoiding cold cracks.